

Information note

N° 056/23

Dear customer,

With this Infineon Technologies AG information note, we would like to inform you about the following

Introduction of new packing materials for product BGSX 44MU18

Management Board Jochen Hanebeck (CEO), Elke Reichart, Dr. Sven Schneider, Andreas Urschitz, Dr. Rutger Wijburg Registered office Neubiberg Commercial register Amtsgericht München HRB 126492



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Products affected

Please refer to attached affected product list "INF_056_23_[customer-no].pdf"

Detailed change information

Subject Introduction of new packing materials for product BGSX 44MU18.

Reason Standardization of packing material for WLGA-18 product.

Description	Old	New
Moisture Barrier Bag (MBB)	 TR-BZD-43 (WVRT ≤ 0.00194g/100in² in 24 hrs.) 	■ IC-BZD-92 (WVRT ≤ 0.00032g/100in ² in 24 hrs.)
Weight of desiccant	■ Desiccant 2 x 5g	■ Desiccant 1 x 20g

► Product identification

Internal traceability ensured via lot number

Impact of change

NO impact on electrical performance of the products as only the packing material will be improved. NO change in form, fit and function.

▶ Attachments

INF_056_23_[customer-no].pdf

affected product list

Intended start of delivery

2024-03-01

If you have any questions, please do not hesitate to contact your local sales office.

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Affected products sold to DIGI-KEY, THIEF RIVER FALLS, USA (4002348)

Sales name	SP number	OPN	Package	Customer part number
BGSX 44MU18 E6327	SP005341854	BGSX44MU18E6327X USA1	WLGA-18-1	BGSX44MU18E6327XUSA